IN THE SPECIFICATION:

Please substitute paragraph **[0002]** for the following starting at page 1, line 13 and ending at line 15.

**[0002]** Image display devices that use electron-releasing elements are recently being developed as substitutes for known cathode-ray-tube display devices because of low-profile, space saving, and lightweight advantages.

Please substitute paragraph **[0005]** for the following starting at page 2, line 8 and ending at line 15.

**[0005]** In the image display device, at the instant when electrons are released from electron-releasing elements (not shown) arranged on the rear plate 1, the electrons are accelerated by applying hundreds to thousands of volts of high voltage to the metal back 5 to collide against the face plate 3, so that fluorescent substances of the fluorescent screen 4 are excited to emit light, thereby displaying an image.

Please substitute paragraph **[0011]** for the following starting at page 3, line 17 and ending at line 23.

**[0011]** It is an object of the present invention to solve the above-described problems of a flat image-display device having a plate spacer, so that even when the center of the spacer is displaced form the initial assembly position, it can easily be corrected to the designed position, to allow a high-quality image display device to be produced with stability.

Please substitute paragraph **[0013]** for the following starting at page 4, line 1 and ending at line 15.

**[0013]** A method for manufacturing an image display device according to the present invention includes the steps of: fixing the ends of the length of a plate spacer to a first substrate while disposing the plate spacer on the surface of the first substrate such that the length of the plate spacer is parallel to the surface of the first substrate ~~and~~; and tightly bonding the first substrate and a second substrate together through the plate spacer while disposing the second substrate to face the first substrate having the plate spacer fixed thereto. The method further includes the step of forming a space between the plate spacer and the surface of the first substrate between the process of fixing the plate space to the first substrate and the process of bonding the first substrate and the second substrate together.

Please substitute paragraph **[0014]** for the following starting at page 4, line 16 and ending at line 17.

**[0014]** ~~preferably~~ Preferably, the process of forming a space is performed by the deformation of the first substrate.

Please substitute paragraph **[0015]** for the following starting at page 4, line 18 and ending at line 21.

**[0015]** ~~preferably~~ Preferably, the process of forming a space is performed by an elastic member provided at the end of the plate spacer. The elastic member is preferably made of a shape-memory alloy.

Please substitute paragraph **[0037]** for the following starting at page 8, line 10 and ending at line 11.

**[0037]** Fig. 15 is a ~~diagrams~~ diagram illustrating the procedure of bonding and fixing the spacer to the rear plate.

Please substitute paragraph **[0056]** for the following starting at page 10, line 19 and ending at line 24.

**[0056]** Fig. 6 shows an example of the structure of a spacer support member, in perspective view, which is used for fastening the plate spacer 7. The support member 9 has a slit 10 along the center line, with one end opened, for the plate spacer 7 to ~~insert~~ be inserted and a through-hole 11 in the deepmost part connecting thereto.

Please substitute paragraph **[0067]** for the following starting at page 13, line 6 and ending at line 14.

**[0067]** Fig. 9 shows the schematic structure of a spacer assembly device. The unit includes a measuring section 32 for measuring the thickness of the plate spacer 7 and the position of the marks 31 formed at the end faces of the plate spacer 7, and a stage 16 for mounting and fixing the rear plate 1, which are arranged in line, and a spacer carrying column 17 arranged to be ~~movably~~ movable in the direction of the arrow a in the drawing, above the measuring section 32 and the rear-plate mount stage 16.

Please substitute paragraph **[0074]** for the following starting at page 15, line 7 and ending at line 19.

**[0074]** Since one ~~of the foots~~ foot of the spacer holder 18 of the spacer carrying column 17 is fixed and the other is movable, the thickness-direction center line of the plate spacer 7 moves with respect to the origin of the device, depending on the thickness of the plate spacer 7. Specifically, as shown in Fig. 11B for example, when the thickness is large by $\Delta t$, the thickness-direction center line of the plate spacer 7 moves toward the movable foot 22 by $\Delta t/2$. Therefore, when the plate spacer 7 is aligned with the rear plate 1, it is necessary to measure the thickness of the plate spacer 7 in advance and to calculate a correction amount, making the alignment correction for each spacer.

Please substitute paragraph **[0084]** for the following starting at page 18, line 2 and ending at line 7.

**[0084]** A proper amount of adhesive 28 is applied to the through-hole 11 of the support member 9 by using the dispenser 19, and the adhesive 28 is thermoset by hot air using the heat gun 20 to bond and fix the plate spacer 7 and the rear plate 1 to each other with a specified positional relationship (Fig. 15).

Please substitute paragraph **[0085]** for the following starting at page 18, line 8 and ending at line 13.

**[0085]** After completion of the thermosetting of the adhesive 28, the pressure of the spacer carrying column 17 is relaxed to move the movable ~~foots~~ feet 22 of the spacer holders 18 in an opening direction, thereby releasing the plate spacer 7 fixed to the rear plate 1 from the space holders 18 (Fig. 14C).

Please substitute paragraph **[0099]** for the following starting at page 23, line 5 and ending at line 16.

**[0099]** The rear plate 1015 has an electron source substrate 1011 fixed thereto, on which n × m cold cathode elements 1012 are formed (n and m are positive integers of 2 or more and are set appropriately depending on the number of target display pixels). For example, it is preferably to set ~~to~~ n = 3,000 and m = 1,000 or more in a display device for high-definition televisions[[)]]. The n × m cold cathode elements 1012 are wired in a simple matrix of m vertical wires 1013 and n transverse wires 1014. The part made of the electron source substrate 1011, the cold cathode elements 1012, the m vertical wires 1013, and n transverse wires 1014 is called a multiple-electron-beam source.

Please substitute paragraph **[0108]** for the following starting at page 25, line 25 and ending at page 26, line 9.

**[0108]** The thickness t of the high-resistance layer 1021 is preferably within the range from 10 nm to 1 μm and, more preferably, from 50 nm to 500 nm. A thin film of 10 nm or less is generally formed in island shape, having unstable resistance and less reproducibility, which depends on the surface energy fo the material, the tightness with the substrate, and substrate temperature. Meanwhile, those with the thickness t of 1 μm or more have larger membrane stress to increase the possibility of peeling-off and ~~takes~~ take a long time for growing, resulting in low productivity.

Please substitute paragraph **[0117]** for the following starting at page 29, line 22 and ending at page 30, line 7.

**[0117]** In the image display device that uses the display panel described above, when voltage is applied to each cold cathode element 1012 through the ex-container terminals Dx1 to Dxm and Dy1 to Dyn, electrons are released from the cold cathode elements 1012, and at the same time, high voltage of hundreds of volts to several kilovolts is applied to the metal back 1019 through the ex-container terminal Hv to accelerate the released electrons to strikes them against the inner surface of the face plate 1017. This excites the respective color fluorescent substances of the fluorescent screen 1018 to emit light, thereby displaying an image.

Please substitute paragraph **[0126]** for the following starting at page 31, line 21 and ending at line 25.

**[0126]** To the rear stage 16, support members 30 are arranged in the position that is substantially parallel to two sides perpendicular to the length of the plate spacer 7, of the four sides of the rear plate 29 with the plate spacer 7, and distance d apart from the two ~~side~~ sides.

Please substitute paragraph **[0140]** for the following starting at page 35, line 2 and ending at line 11.

**[0140]** The low-resistance layer 1022 was formed on the image forming region for the purpose of electrical connection between the high-resistance layer 1021 of the spacer 1020 and the face plate 1017 and between the high-resistance layer 1021 and the rear plate 1015 (in this example, the vertical wires 1013 on the electron source substrate 1011 are bonded and fixed on the rear plate 1015) and also for the purpose of restraining the electric field around the spacer 1020 to control the path of electronic beams from the electron-releasing elements.

Please substitute paragraph **[0145]** for the following starting at page 36, line 12 and ending at line 22.

**[0145]** The spacer 1020 was aligned by a spacer assembling unit in the center of the vertical wires 1013 in the electron-beam releasing region of the rear plate 1015 so as to be perpendicular to the surface of the rear plate 1015, and the spacer-support members 1030 joined to the opposite ends were each fixed on the rear plate 1015 with a second joint member 1053. Also in this example, the plurality of spacers 1020 was fixed on the rear plate 1015 with longitudinal tension loaded thereto, in accordance with the procedure in the description of the embodiments of the invention.